



# HI-SINCERITY MICROELECTRONICS CORP.

Spec. No. : HE9505-B  
Issued Date : 1996.04.09  
Revised Date : 2000.10.01  
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## HM6718

NPN EPITAXIAL PLANAR TRANSISTOR

### Description

The HM6718 is designed for general purpose medium power amplifier and switching.

### Features

- High power: 1W
- High current: 1A

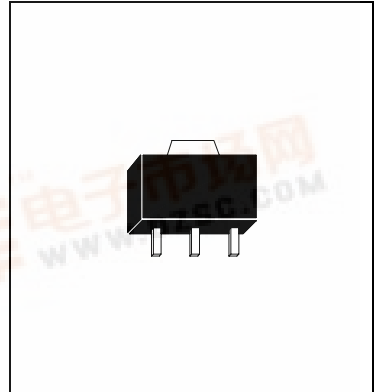
### Absolute Maximum Ratings

- Maximum Temperatures  
Storage Temperature ..... -55 ~ +150 °C  
Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation  
Total Power Dissipation (Ta=25°C) ..... 1 W
- Maximum Voltages and Currents (Ta=25°C)  
VCBO Collector to Base Voltage ..... 100 V  
VCEO Collector to Emitter Voltage ..... 100 V  
VEBO Emitter to Base Voltage ..... 5 V  
IC Collector Current ..... 1 A

### Characteristics (Ta=25°C)

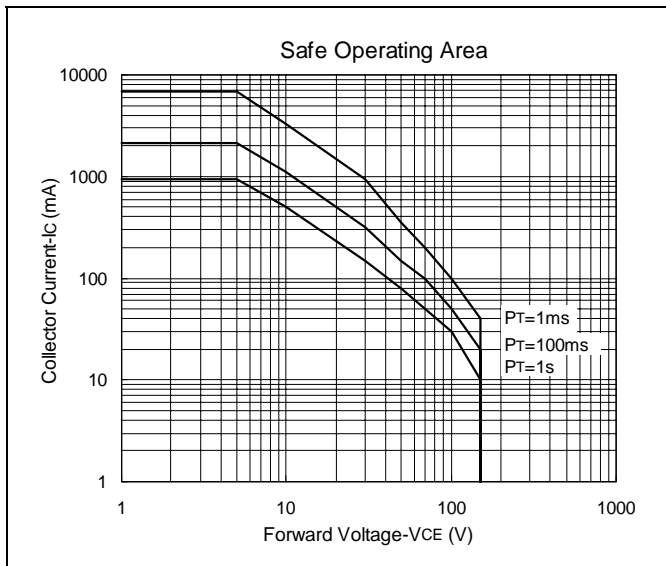
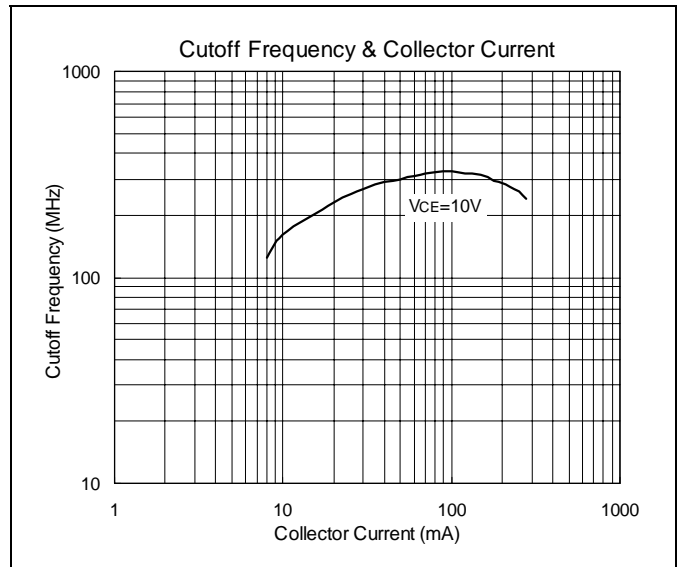
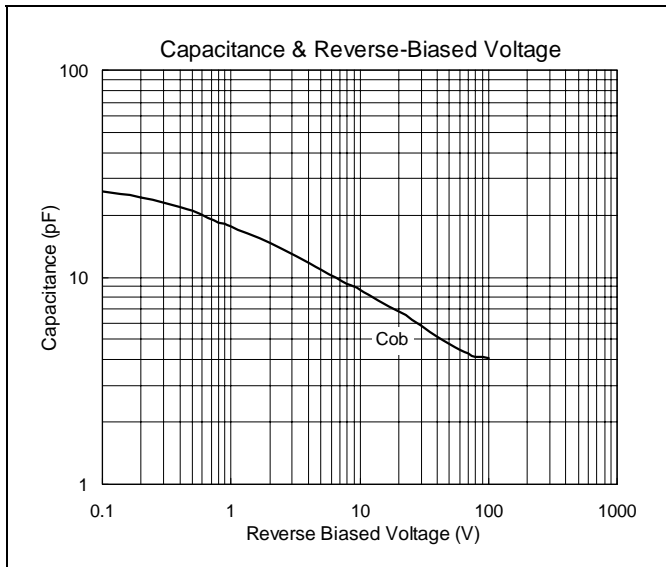
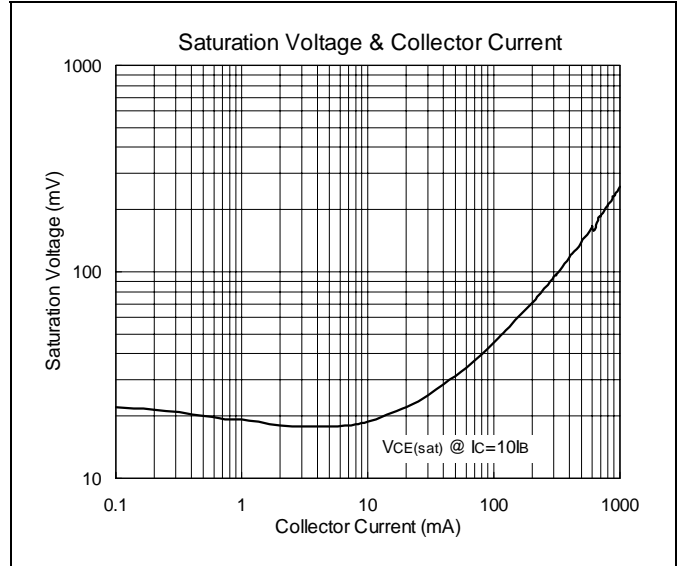
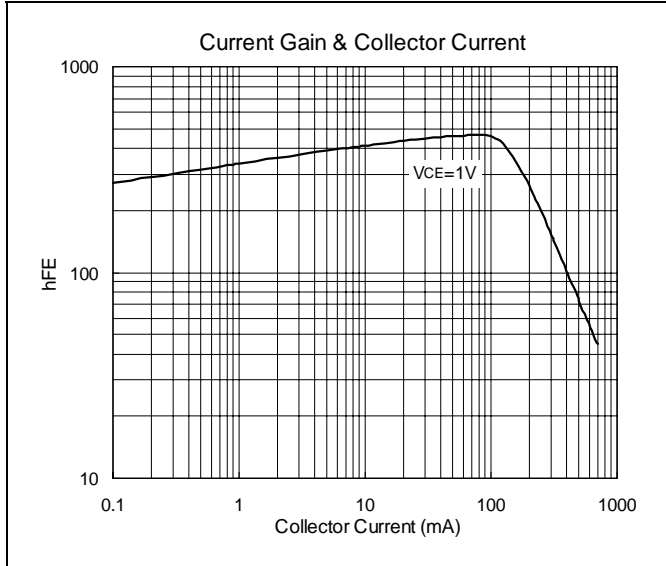
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	100	-	-	V	IC=100uA
BVCEO	100	-	-	V	IC=1mA
BVEBO	5	-	-	V	IE=10uA
ICBO	-	-	100	nA	VCB=80V
*VCE(sat)	-	-	350	mV	IC=350mA, IB=35mA
*hFE1	80	-	-		VCE=1V, IC=50mA
*hFE2	100	-	250		VCE=1V, IC=250mA
*hFE3	20	-	-		VCE=1V, IC=500mA
fT	50	-	-	MHz	VCE=10V, IC=50mA, f=100MHz
Cob	-	-	20	pF	VCB=10V, f=1MHz

\*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



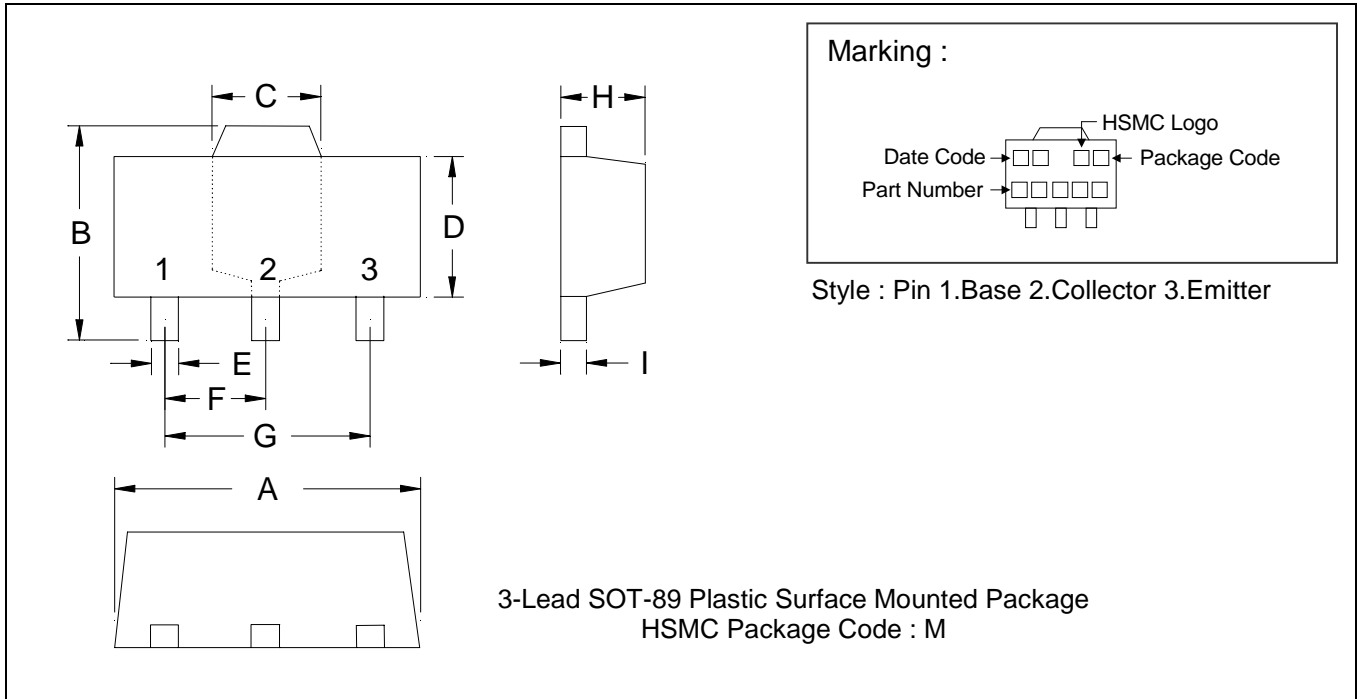


### Characteristics Curve





### SOT-89 Dimension



\*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.52
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.0141	0.0201	0.36	0.51					

Notes : 1.Dimension and tolerance based on our Spec. dated May. 05,1996.  
 2.Controlling dimension : millimeters.  
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material :**

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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